

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2685527

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TAKAAKI TSUNOMURA</td> <td>12/21/2013</td> </tr> <tr> <td>TOSHIAKI IWAMATSU</td> <td>11/14/2013</td> </tr> </tbody> </table>		Name	Execution Date	TAKAAKI TSUNOMURA	12/21/2013	TOSHIAKI IWAMATSU	11/14/2013				
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Renesas Electronics Corporation</td> </tr> <tr> <td>Street Address:</td> <td>1753, Shimonumabe, Nakahara-ku</td> </tr> <tr> <td>City:</td> <td>Kawasaki-shi, Kanagawa</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>211-8668</td> </tr> </table>		Name:	Renesas Electronics Corporation	Street Address:	1753, Shimonumabe, Nakahara-ku	City:	Kawasaki-shi, Kanagawa	State/Country:	JAPAN	Postal Code:	211-8668
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CORRESPONDENCE DATA											
<p>Fax Number: (202)672-5399          Phone: 202-672-5300          Email: rhale@foley.com  <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>          Correspondent Name: FOLEY &amp; LARDNER LLP          Address Line 1: 3000 K STREET NW          Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20007</p>											
ATTORNEY DOCKET NUMBER:	104404-0104										
NAME OF SUBMITTER:	EFFIE HALE FOR GEORGE C. BECK										
Signature:	/Effie Hale/										
Date:	01/16/2014										
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif											

ASSIGNMENT  
( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation,  
a corporation organized under the laws of Japan,  
located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan,  
receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation,  
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND  
MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation,  
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) Takaaki Tsunomura (Takaaki TSUNOMURA)

December 21, 2013

2) \_\_\_\_\_ (Toshiaki IWAMATSU)

3) \_\_\_\_\_

4) \_\_\_\_\_

5) \_\_\_\_\_

6) \_\_\_\_\_

**ASSIGNMENT**  
( 譲 渡 証 )

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INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) \_\_\_\_\_ (Takaaki TSUNOMURA)

2) Toshiaki Iwamatsu (Toshiaki IWAMATSU)

November 14, 2013

3) \_\_\_\_\_

4) \_\_\_\_\_

5) \_\_\_\_\_

6) \_\_\_\_\_